

Incorporation of fillers in elastomeric composites: impact of the process on the thermomechanical properties

Adrien Simon, Daphné Berthier, Marie-Pierre Deffarges, Mathieu Venin,

Florian Lacroix, Yoann Tendron, Stéphane Méo

▶ To cite this version:

Adrien Simon, Daphné Berthier, Marie-Pierre Deffarges, Mathieu Venin, Florian Lacroix, et al.. Incorporation of fillers in elastomeric composites: impact of the process on the thermomechanical properties. IRC 2019, Sep 2019, London, United Kingdom. hal-02294357

HAL Id: hal-02294357 https://univ-tours.hal.science/hal-02294357v1

Submitted on 23 Sep 2019

HAL is a multi-disciplinary open access archive for the deposit and dissemination of scientific research documents, whether they are published or not. The documents may come from teaching and research institutions in France or abroad, or from public or private research centers. L'archive ouverte pluridisciplinaire **HAL**, est destinée au dépôt et à la diffusion de documents scientifiques de niveau recherche, publiés ou non, émanant des établissements d'enseignement et de recherche français ou étrangers, des laboratoires publics ou privés.











Conference Organisation Incorporation of fillers in elastomeric composites: impact of the process on the thermomechanical properties

<u>Adrien Simon, Daphné Berthier², Marie-Pierre Deffarges¹, Mathieu Venin¹, Florian Lacroix¹, Yohan Tendron², Stéphane Méo¹</u>

¹ Laboratoire de Mécanique Gabriel Lamé, Université de Tours, Université d'Orléans, INSA Centre Val de Loire, Polytech Tours, 7 avenue Marcel Dassault BP40, 37004 Tours, France ² SAFRAN AEROSYSTEMS, 20 Avenue Georges Pompidou, 37600 Loches, France

* In partnership with the LRCCP (Laboratoire de Recherche et de Contrôle du Caoutchouc et des Plastiques)

Previous works [1] led to the development of a new formula on the basis of FKM blend reinforced with Polyhedral Oligomeric Silesesquioxanes (POSS). The main objective consists in maintaining thermomechanical properties while changing the process scale. To this end, two new specimen geometries of vulcanized rubber are studied : thin films obtained by coating at laboratory scale through masterbatch and sheets obtained through rubber mill and thermocompression.

Fluorinated rubber: FKM

Polyhedral Oligomeric SilSesquioxanes (POSS)



Formula of the terpolymer FKM

- \succ A fourth monomer is incorporated to enhance the crosslinking action, named « Cure Site Monomer » (CSM)
- FKM exhibits good mechanical, chemical and thermal properties



Chemical structure of POSS

Smallest silica particles (1 to 3nm) > Hybrid chemical composition Role of functionnal groups (X) : chemical interaction with polymers



Possible interactions with a POSS (X=1) [2]







Conclusions

 \succ Impact of the process and of the specimen geometries on the macroscopic mechanical characterisation (by tensile test : underestimation of the materials properties on thin films), on the glass transition and on the cross linking reaction (on activation energy and activation temperature) \succ Presence of volatile compounds in thin films but not in sheets (TGA) results)

> No impact on degradation behaviour

>Thin films is a cost efficient way to provide thermal informations before sheet fabrication

Perspectives Upgrade of the formula Processes and geometries Incorporation of POSS with new Impact of a new manufacturing way (tube by) functionnal groups extrusion) final > Characterisation of materials after between the three Comparison chemical and/or thermal aging products (thin film-sheet-tube)

[1] D. Berthier, M-P. Deffarges, N. Berton, M. Venin, F. Lacroix, B. Schmaltz, Y. Tendron, E. Pestel, F. Tran-Van, S. Méo. "POSS Nanofiller-Induced Enhancement of the Thermomechanical Properties in a Fluoroelastomer Terpolymer", Materials, 11(8): 1358, 2018. [2] K. Raftopoulos, K. Pielichowski, « Segmental dynamics in hybrid polymer/POSS nanomaterials », Prog. Polym. Sci. 52 136–187, 2016. [3] S.-R. Tseng, H.-F. Meng, K.-C. Lee, and S.-F. Horng, "Multilayer polymer light-emitting diodes by blade coating method," Appl. Phys. Lett., vol. 93, no. 15, p. 153308, Oct. 2008.